L Number	Hits	Search Text	DB	Time stamp
1	2612713	semiconductor die chip ic (integrated adj circuit) microprocessor	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/02/24 14:11
2	698909	(substrate board carrier) same (semiconductor die chip ic (integrated adj circuit) microprocessor)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/02/24 14:12
3	135272	gasket lossy polytetrafluorethylene	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/24 14:13
4	1	gasket and lossy and polytetrafluorethylene	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/24 14:13
5	6020	(semiconductor die chip ic (integrated adj circuit) microprocessor) and ((substrate board carrier) same (semiconductor die chip ic (integrated adj circuit) microprocessor)) and (gasket lossy polytetrafluorethylene)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 14:13
6	2231		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 14:16
7	763		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 14:22

L Number	Hits	Search Text	DB	Time stamp
1	2612713	semiconductor die chip ic (integrated adj circuit) microprocessor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/24 14:11
2	698909	(substrate board carrier) same (semiconductor die chip ic (integrated adj circuit) microprocessor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/24 14:12
3	135272	gasket lossy polytetrafluorethylene	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/02/24 14:13
4	1	gasket and lossy and polytetrafluorethylene	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/02/24 16:48
5	6020	(semiconductor die chip ic (integrated adj circuit) microprocessor) and ((substrate board carrier) same (semiconductor die chip ic (integrated adj circuit) microprocessor)) and (gasket	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 14:13
6	2231	lossy polytetrafluorethylene) (esd shielding shielded shield electrostic discharge) and ((semiconductor die chip ic (integrated adj circuit) microprocessor) and ((substrate board carrier) same (semiconductor die chip ic (integrated adj circuit) microprocessor)) and (gasket	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 14:16
7	763	lossy polytetrafluorethylene)) (heat with (speader sink metal radiate thermal dissipate dissipative dissipating)) and ((esd shielding shielded shield electrostic discharge) and ((semiconductor die chip ic (integrated adj circuit) microprocessor) and ((substrate board carrier) same (semiconductor die chip ic (integrated adj circuit) microprocessor)) and (gasket lossy polytetrafluorethylene)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24
8	4594	polytetrafluorethylene	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/24 16:32
9		((heat with (speader sink metal radiate thermal dissipate dissipative dissipating)) and ((esd shielding shielded shield electrostic discharge) and ((semiconductor die chip ic (integrated adj circuit) microprocessor) and ((substrate board carrier) same (semiconductor die chip ic (integrated adj circuit) microprocessor)) and (gasket lossy polytetrafluorethylene)))) and polytetrafluorethylene	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/24 16:32
10	88	(gasket lossy) same polytetrafluorethylene	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/24 16:48

11	1	(semiconductor die chip ic (integrated	USPAT;	2004/02/24
		adj circuit) microprocessor) same	US-PGPUB;	16:50
		((gasket lossy) same	EPO; JPO;	
		polytetrafluorethylene)	DERWENT;	
			IBM TDB	1
12	8	(semiconductor die chip ic (integrated	USPAT;	2004/02/24
		adj circuit) microprocessor) and ((gasket	US-PGPUB;	16:50
		lossy) same polytetrafluorethylene)	EPO; JPO;	
			DERWENT;	
			IBM TDB	